COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP20396</th>
<th>REV: B</th>
<th>SUN REV: Not In VersionControl</th>
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<tr>
<td>TID #: N/A</td>
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<tr>
<th>PLOT NAME = Top Assembly Drawing</th>
<th>GENERATED: 2/14/2017 8:58:42 AM</th>
<th>TEXAS INSTRUMENTS</th>
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